

- UL recognition, file #E313149
- Ideal for automated placement
- Glass passivated chip junction
- High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

General purpose use in high frequency AC/DC bridge full wave rectification for power supply, lighting ballast, battery charger, home appliances, office equipment, and telecommunication applications.

- : MBLS
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- : Tin plated 100

Maximum DC blocking Voltage	V _{DC}	V	600	800	1000
Average rectified output current @60Hz sine wave, R-load, T _c =115	I _O	A	1.0		
Forward Surge Current (Non-repetitive) @8.3ms Half-sine wave, 1 cycle, T _j =25	I _{FSM}	A	30		
Current squared time @1ms≤t≤8.3ms T _j =25, rating of per diode	I ² t	A ² s	3.7		
Storage temperature	T _{stg}		-55 ~ +150		
Junction temperature	T _j		-55 ~ +150		

T_a=25 Unless otherwise specified

Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	75	
Maximum instantaneous forward voltage drop per diode	V _F	V	I _{FM} =0.5A	1.7	
Maximum DC reverse current at rated DC blocking voltage per diode	I _R	μA	T _j =25	5	
			T _j =125	100	
Typical junction capacitance	C _j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	12	



■ Ta=25 Unless otherwise specified

Typical Thermal Resistance	Between junction and ambient	RθJ-A	/W	65.0		
	Between junction and lead	RθJ-L		28.0		
	Between junction and case	RθJ-C		18.0		

Note: Device mounted on P.C.B with 35mm*25mm*1.7mm.

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or